IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	Material Compos © Copyright 2005. IPC international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Type Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfa Information			
upplier Infor												3			
Company name* Company			Company uni	nique ID			Unique ID Authority				Respon	Response Date*			
onsemi										2024-0	2024-04-19				
Contact Name			Title - Contact			I	Phone - Contact*				Email	Email - Contact*			
Product-Env-Stev	wards		Product Enviro Compliance]	NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			F	Phone - Representative*			Email	Email - Representative*				
Product-Env-Stewards Product Enviro Co			ro Compliance		NA Product-Env-Stewards@onsemi.com					om					
Reques	ster Item Number	Mfr Item I	Number	Mfr Item Name			Effective Date	Version	Version Manufacturing Site			Weight*	UOM	Unit Type	
		AR0132A A0-DRBR	T6C00XPE	1.2 MP 1/3 CIS			2024-04-19			MY5		198.94	mg	Each	
I anufacturing	g Proccess Informatio	on													
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-02			J-STD-020 MSI	L Rating	Peak Proc	ess Body	Temperatu	re Max Time at Pea	k Tempera	nture Num	ber of Reflow Cyc	eles			
SnAgCu CU Al		J Alloy	3	3		260		С	30	seco	nds 3				
omments	·			·						·			·		
TTENTION: M	SL 3 Rated item requires B	Bake and Dr	y Pack (after	electrical test)											
or more informa	tion regarding material co	mposition p	lease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	46.746	mg		Misc.	proprietary data		0.1776	mg
			Supplier	Silicon (Si)	7440-21-3		46.1056	mg
			Supplier	Aluminum (Al)	7429-90-5		0.4628	mg
Die Attach	2.852	mg		Bismaleimide Monomer	proprietary data		1.098	mg
			Supplier	POLY(ETHYLENE GLYCOL) PHENYL ETHER ACRYLATE	56641-05-5		0.0143	mg
			Supplier	2,2-Bis(4-hydroxyphenyl)propane- epichlorohydrin copolymer acrylate	55818-57-0		0.2852	mg
			Supplier	Bis(4-tert-butylcyclohexyl) peroxydicarbonate	15520-11-3		0.0143	mg
			Supplier	2,2-dimethyl-1,3-propanediyl dimethacrylate	1985-51-9		0.2852	mg
			Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.2852	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0143	mg
			Supplier	Other Additive Agents	Proprietary Data		0.5704	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.2852	mg
Imaging Lens	29.239	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.5388	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.5388	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.5388	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.1541	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.5388	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.5388	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		21.3907	mg
Lid Attach	1.459	mg	Supplier	2,2-Bis(glycidyloxyphenyl)propane polymer	25085-99-8		0.3647	mg
			Supplier	3,4-EPOXYCYCLOHEXYLMETHYL	2386-87-0		1.0578	mg
			Supplier	Misc.	Proprietary Data		0.0365	mg
Mold Compound	43.49	mg		Epoxy resin	proprietary data		10.7855	mg
			Supplier	Other Additive Agents	Proprietary Data		1.3917	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.349	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.6591	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.3047	mg
Solder Ball	35.868	mg	Supplier	Silver (Ag)	7440-22-4		1.076	mg

			Supplier	Tin (Sn)	7440-31-5	34.6126	mg
			Supplier	Copper (Cu)	7440-50-8	0.1793	mg
Solder Mask	4.22	mg		Epoxy resin	proprietary data	0.5064	mg
			Supplier	Acrylate	Proprietary Data	1.612	mg
			Supplier	Talc	14807-96-6	0.1139	mg
			Supplier	Miscellaneous	Trade Secret	0.1561	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	1.8315	mg
Substrate Copper Foil	3.09	mg	Supplier	Copper (Cu)	7440-50-8	3.09	mg
Substrate - Core Material	16.24	mg		Epoxy resin	proprietary data	3.5192	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3	12.7208	mg
Substrate Plating-Au	0.29	mg	Supplier	Gold (Au)	7440-57-5	0.29	mg
Substrate Plating-Cu	14.49	mg	Supplier	Copper (Cu)	7440-50-8	14.49	mg
Substrate Plating-Ni	0.67	mg	В	Nickel (Ni)	7440-02-0	0.67	mg
Wire Bond - Au	0.286	mg	Supplier	Gold (Au)	7440-57-5	0.286	mg